

November 2013

FQD19N10

N-Channel QFET® MOSFET 100 V, 15.6 A, 100 m Ω

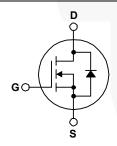
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- 15.6 A, 100 V, $R_{DS(on)}$ = 100 m Ω (Max.) @ V_{GS} = 10 V, I_D = 7.8 A
- Low Gate Charge (Typ. 19 nC)
- Low Crss (Typ. 32 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FQD19N10TM	Unit
V_{DSS}	Drain-Source V	Voltage		100	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		C)	15.6	А
			9.8	Α	
I _{DM}	Drain Current	- Pulsed	(Note 1)	62.4	Α
V _{GSS}	Gate-Source Vo	te-Source Voltage		± 25	V
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	220	mJ
I _{AR}	Avalanche Current		(Note 1)	15.6	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	5.0	mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	6.0	V/ns
P_{D}	Power Dissipation (T _A = 25°C) *			2.5	W
	Power Dissipation (T _C = 25°C)			50	W
	- Derate above 25°C			0.4	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FQD19N10TM	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.5	
ID	Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.	110	°C/W
	Thermal Resistance, Junction to Ambient (*1 in ² Pad of 2-oz Copper), Max.	50	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQD19N10TM	FQD19N10	D-PAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions		Тур.	Max.	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient Breakdown Voltage Temperature LD = 250 μA, Referenced to 25°C			0.1		V/°C
I _{DSS}	Zana Cata Valtana Dunin Cumant	V _{DS} = 100 V, V _{GS} = 0 V		-	1	μА
Ze	Zero Gate Voltage Drain Current	V _{DS} = 80 V, T _C = 125°C		-	10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -25 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 7.8 A		0.078	0.1	Ω
g _{FS}	Forward Transconductance $V_{DS} = 40 \text{ V}, I_D = 7.8 \text{ A}$			11		S
	ic Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		600	780	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		165	215	pF
C _{rss}	Reverse Transfer Capacitance			32	40	pF
Switchi	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 50 V, I _D = 19 A,		7.5	25	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		150	310	ns
t _{d(off)}	Turn-Off Delay Time	1.6 2012		20	50	ns
t _f	Turn-Off Fall Time	(Note 4)		65	140	ns
Qg	Total Gate Charge	V _{DS} = 80 V, I _D = 19 A,		19	25	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		3.9		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	/	9.0		nC
Drain-S	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Did			15.6	Α	
I _{SM}	Maximum Pulsed Drain-Source Diode F	Forward Current			62.4	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 15.6 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 19 A,		78	>	ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs		200	//	nC

Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 1.35 mH, I_{AS} = 15.6 A, V_{DD} = 25 V, R_G = 25 Ω , starting T_J = 25°C. 3. $I_{SD} \le 19$ A, di/dt ≤ 300 A/ μ s, $V_{DD} \le BV_{DSS}$, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

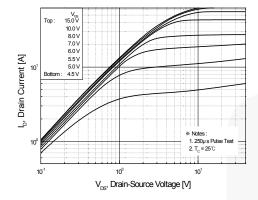


Figure 1. On-Region Characteristics

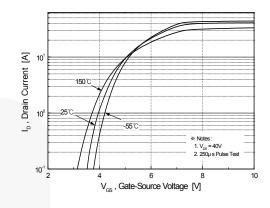


Figure 2. Transfer Characteristics

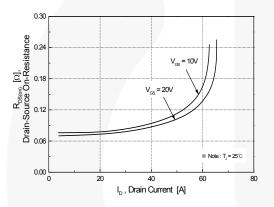


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

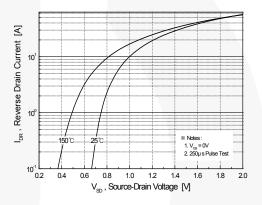


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

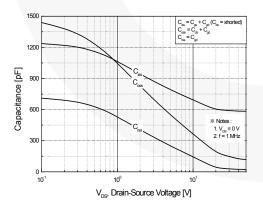


Figure 5. Capacitance Characteristics

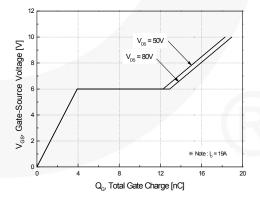


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

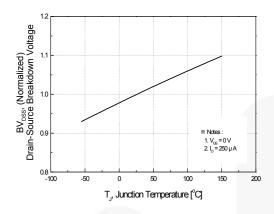
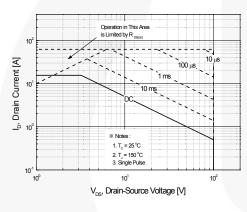


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



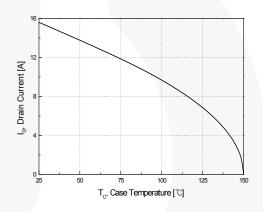


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

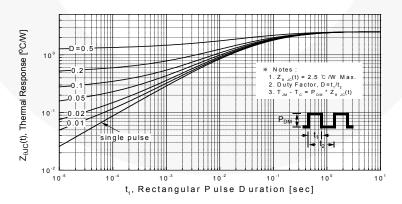


Figure 11. Transient Thermal Response Curve

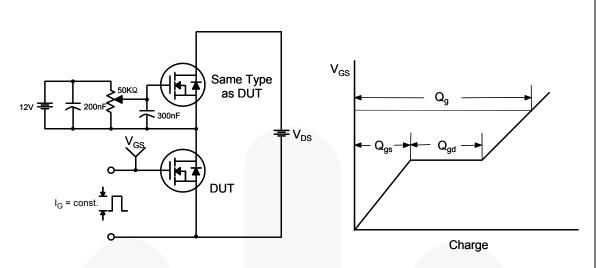


Figure 12. Gate Charge Test Circuit & Waveform

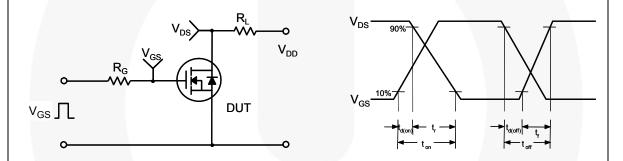


Figure 13. Resistive Switching Test Circuit & Waveforms

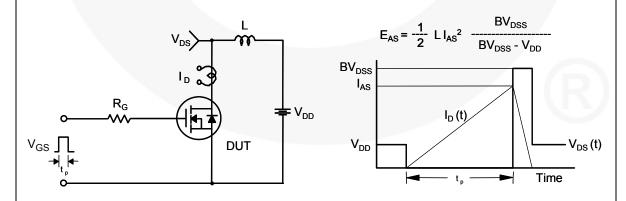
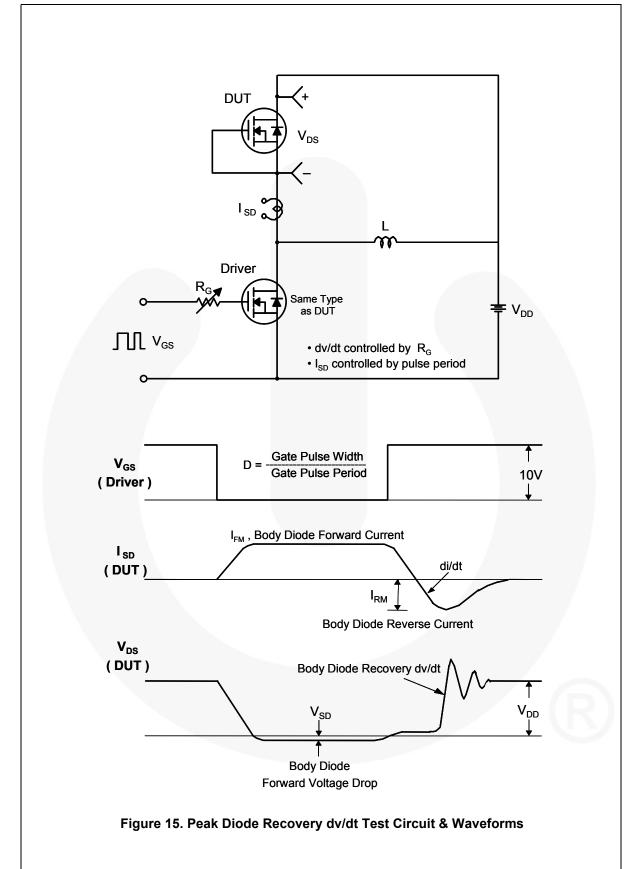


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

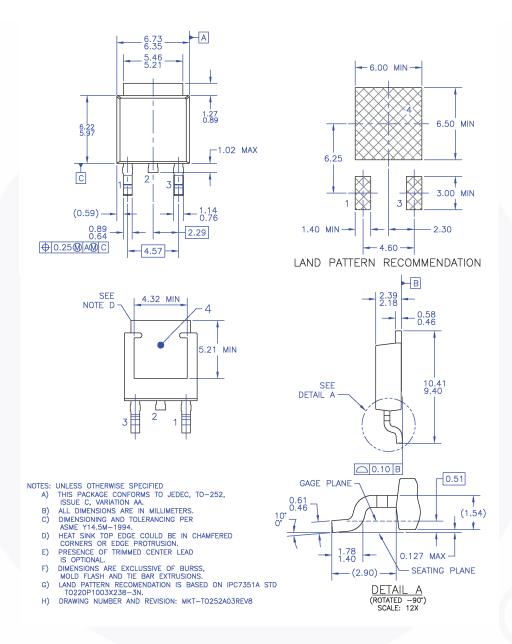


Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/package/packageDetails.html?id=PN_TT252-003





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ AX-CAP® BitSiC™ Build it Now™ CorePLUS™ CorePOWER™

 $CROSSVOLT^{\text{TM}}$ CTI ™ Current Transfer Logic™ DEUXPEED®

Dual Cool™ EcoSPARK® EfficentMax™ ESBC™

Fairchild[®]

Fairchild Semiconductor® FACT Quiet Series™ FACT® FAST® FastvCore™ FETBench™

F-PFS™ FRFET® Global Power ResourceSM

GreenBridge™ Green FPS™

Green FPS™ e-Series™

G*max*™ GTO™ IntelliMAX™ ISOPLANAR™

Marking Small Speakers Sound Louder

and Better™ MegaBuck™ MICROCOUPLER™ MicroFET™ MicroPak™

MicroPak2™ MillerDrive™ MotionMax™ mWSaver® OptoHiT™ OPTOLOGIC® OPTOPLANAR® PowerTrench® PowerXS™

Programmable Active Droop™

QFET QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™ SignalWise™

SmartMax™ SMART START™

Solutions for Your Success™

STEALTH™

SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SvncFET™

Sync-Lock™ SYSTEM®*

TinyBoost[®] TinyBuck[®] TinyCalc™ TinyLogic[®] TINYOPTO™ TinvPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™ TRUECURRENT®*

UHC[®] Ultra FRFET™ UniFFT™ VCX™

μSerDes™

VisualMax™ VoltagePlus™ XSTM

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FPS™

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE
EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS Definition of Terms

Datasheet Identification Product Status		Definition		
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specification may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete Not In Production		Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 166